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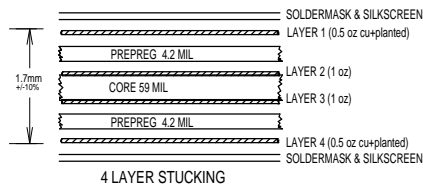
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5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,4	5.0	N/A	55 OHM	N/A	+/-10%
1	6.1	8.9	N/A	90 OHM	+/-10%
1	5.1	9.9	N/A	100 OHM	+/-10%

4 LAYER STACK-UP



REVISIONS

REV	DESCRIPTION	DATE	APPROVED
1.0	EDITION ORIGINALE	2008-**-**	***

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS					
FIGURE	SIZE	TOLERANCE	PLATED	ROTATION	QTY
•	12.0	+3.0/-3.0	PLATED	-	574
◻	30.0	+3.0/-3.0	PLATED	-	18
◦	32.0	+3.0/-3.0	PLATED	-	3
◦	36.0	+3.0/-3.0	PLATED	-	118
◦	38.0	+3.0/-3.0	PLATED	-	18
◦	40.0	+3.0/-3.0	PLATED	-	139
△	48.0	+3.0/-3.0	PLATED	-	6
◦	53.0	+3.0/-3.0	PLATED	-	2
○	95.0	+3.0/-3.0	PLATED	-	4
◻	28.0	+2.0/-2.0	NON-PLATED	-	3
◦	38.0	+2.0/-2.0	NON-PLATED	-	2
△	39.0	+2.0/-2.0	NON-PLATED	-	1
B	47.0	+2.0/-2.0	NON-PLATED	-	3
C	58.0	+2.0/-2.0	NON-PLATED	-	1
D	59.0	+2.0/-2.0	NON-PLATED	-	2
E	79.0	+2.0/-2.0	NON-PLATED	-	2
F	87.0	+2.0/-2.0	NON-PLATED	-	2
G	126.0	+2.0/-2.0	NON-PLATED	-	2
H	138.0	+2.0/-2.0	NON-PLATED	-	6
∞	83.0x36.0	+5.0/-5.0	PLATED	0.000	4
∞	110.0x36.0	+5.0/-5.0	PLATED	0.000	4
∞	126.0x40.0	+5.0/-5.0	PLATED	0.000	1
∞	126.0x40.0	+5.0/-5.0	PLATED	90.000	2
∞	140.0x50.0	+5.0/-5.0	PLATED	90.000	4

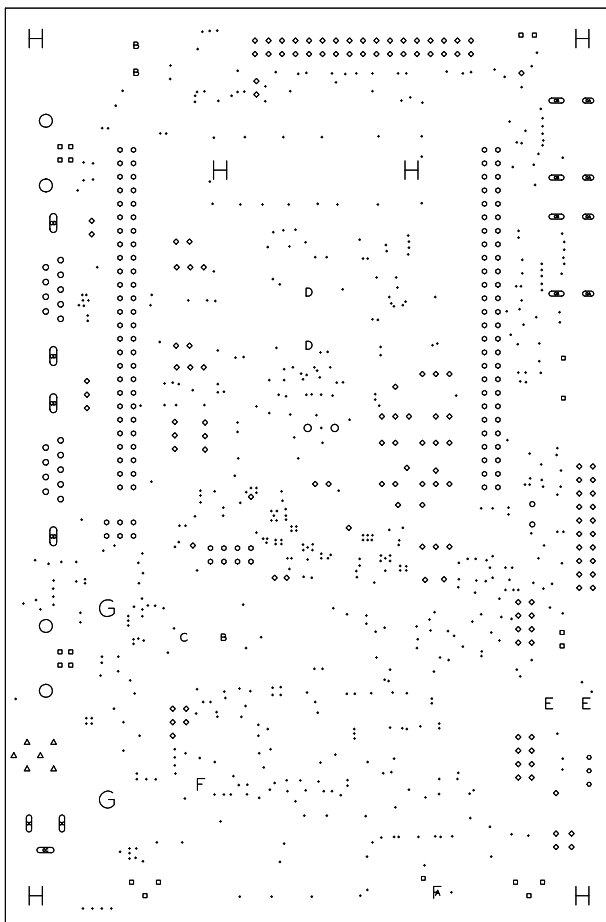
TOTAL HOLES: 921

PCB SPECIFICATIONS:

- A. MATERIAL; FR-4, ☒ TG-170 ☐ TG-150 ☐ TG-140
- B. MATERIAL FAMILY; N/A.
- C. SOLDERMASK COLOR; ☒ GREEN ☐ BLUE ☐ RED ☐ BLACK
- D. SILKSCREEN COLOR; ☒ WHITE ☐ YELLOW ☐ BLACK
- E. SURFACE FINISH; ☒ ENIG ☐ IMMERSION SILVER ☐ IMMERSION TIN ☐ HASL ☐ HASL(PB-FREE) ☐ GOLDEN FINGER
- F. IMPEDANCE CONTROL; ☐ NO ☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- G. THROUGH VIA; PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL: ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
- H. STACK-UP; SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB REQUIREMENTS:

- THIS BOARD WILL CONFORM TO:
IPC-A-600, CURRENT REV., CLASS II
IPC-6012, CURRENT REV., CLASS II
- UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.
ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY COROSS SECTION.
- MATERIAL FR4 RATING 94V-0 MINIMUM EPOXY GLASS LAMINATE.
- BOARD SHALL BE LPI SOLDER MASKED OVER BARE COPPER BOTH SIDES PER IPC-SM-840 CLASS II.
- SILKSCREEN SHALL BE PERMANENT NON-CONDUCTIVE INK AND WITH NO OVERLAP ON ANY COMPONENT PAD OR THROUGH HOLE.
- MFGR, TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK
A. U.I. CODE D. MFGR. LOGO
B. DATE CODE E. SUCCESSFUL ELECTRICAL BOARD TEST.
C. FLAMMABILITY RATING
- REMOVE THE FLASHS WHICH SMALLER THAN HOLE SIZE.
- REMOVE ALL SHAPE EDGES AND BURRS .005 MAXIMUM.
- PLEASE USE THE SUPPLIED IPC 356 NETLIST TO VERIFY BOARD BEFORE FABRICATING BOARD.

DESIGNED BY SOFER
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Mail: design@sofer.com.cnLAYER:
FAB DAWING & DRILL LEGEND

DESIGNER: Shelley

DATE: 2013.08.19

COMPANY NAME:

ST

PROJECT NAME:

MB1070

PROJECT NUMBER:

D031-007A2

REV B

UNLESS OTHERWISE SPECIFIED

SIGNATURES

DATE

DIMENSIONS ARE IN INCHES
TOLERANCES ON:
2 PL DECIMALS +
3 PL DECIMALS +
ANGLES +
FRACTIONS +

DRAWN

YY-MM-DD

CHECKED

YY-MM-DD

ENGRG

YY-MM-DD

ISSUED

LOGO

COMPANY NAME

TITLE

PROJECT NAME *

SIZE B

DWG NO

REV **

SCALE 1:1

SHEET

1 OF 1